

General Description

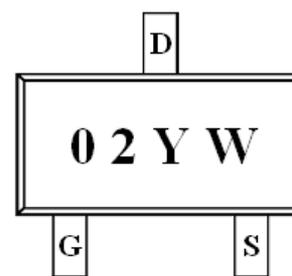
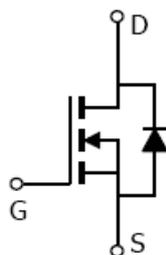
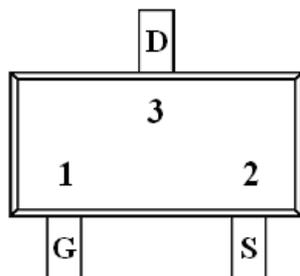
AFN7402, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

- 20V/3.6A, $R_{DS(ON)}=60m\Omega@V_{GS}=4.5V$
- 20V/3.2A, $R_{DS(ON)}=70m\Omega@V_{GS}=2.5V$
- 20V/2.8A, $R_{DS(ON)}=90m\Omega@V_{GS}=1.8V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-323 package design

Pin Description (SOT-323)



Application

- Portable Equipment
- Battery Powered System
- Net Working System

Pin Define

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN7402S32RG	02YW	SOT-323	Tape & Reel	3000 EA

- ※ 02 parts code
- ※ Y year code (0 ~ 9)
- ※ W week code (A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52)
- ※ AFN7402S32RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



Absolute Maximum Ratings

($T_A=25^{\circ}\text{C}$ Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate –Source Voltage	V_{GSS}	± 12	V
Continuous Drain Current($T_J=150^{\circ}\text{C}$)	I_D	$T_A=25^{\circ}\text{C}$	3.6
		$T_A=70^{\circ}\text{C}$	2.6
Pulsed Drain Current	I_{DM}	10	A
Continuous Source Current(Diode Conduction)	I_S	1.6	A
Power Dissipation	P_D	$T_A=25^{\circ}\text{C}$	0.35
		$T_A=70^{\circ}\text{C}$	0.22
Operating Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55/150	$^{\circ}\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	120	$^{\circ}\text{C}/\text{W}$

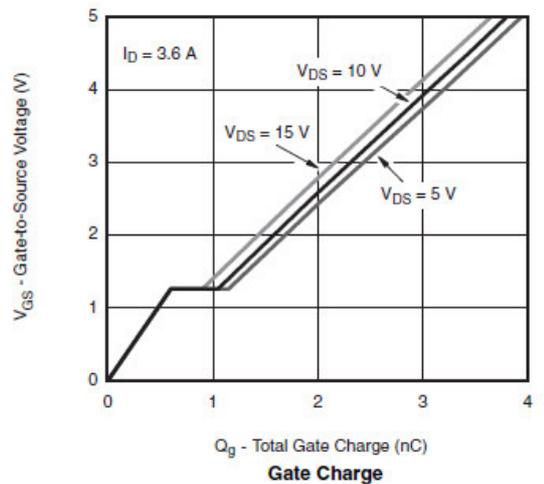
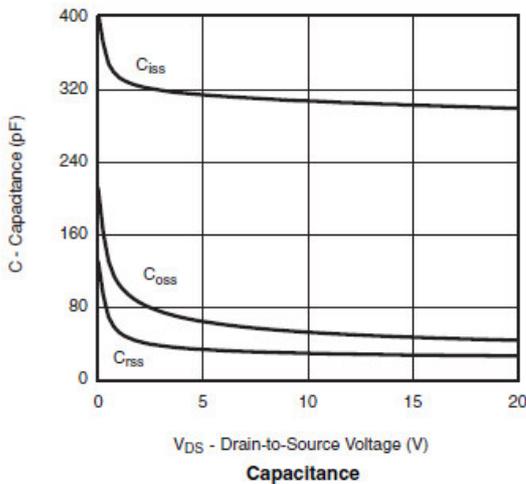
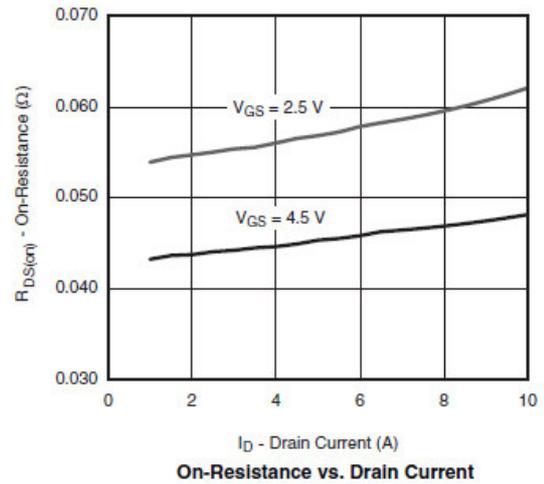
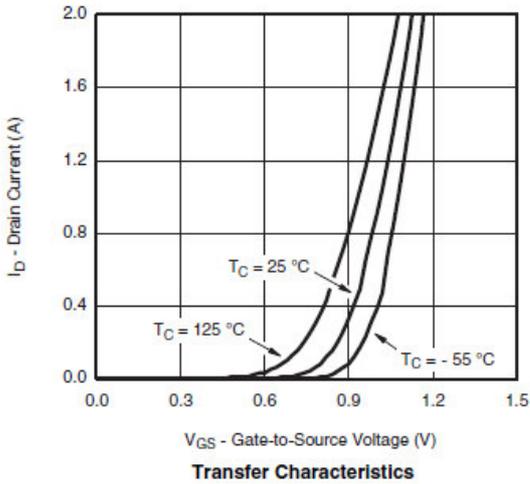
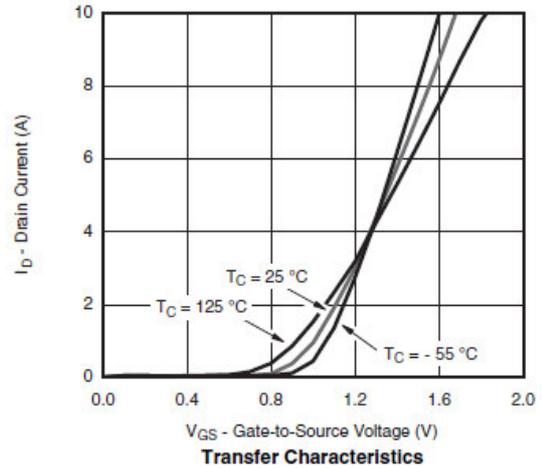
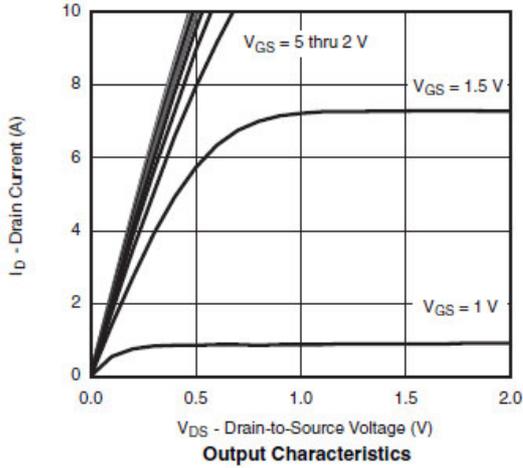
Electrical Characteristics

($T_A=25^{\circ}\text{C}$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.3		0.8	
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 12V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=16V, V_{GS}=0V$			1	uA
		$V_{DS}=16V, V_{GS}=0V$ $T_J=85^{\circ}\text{C}$			10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5V, V_{GS}=4.5V$	6			A
		$V_{DS} \geq 5V, V_{GS}=2.5V$	4			
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=3.6A$		52	60	m Ω
		$V_{GS}=2.5V, I_D=3.2A$		62	70	
		$V_{GS}=1.8V, I_D=2.8A$		78	90	
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=3.6A$		10		S
Diode Forward Voltage	V_{SD}	$I_S=1.6A, V_{GS}=0V$		0.85	1.2	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=10V, V_{GS}=4.5V$ $I_D=3.6A$		4.2	5.0	nC
Gate-Source Charge	Q_{gs}			0.6		
Gate-Drain Charge	Q_{gd}			0.4		
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V$ $f=1\text{MHz}$		340		pF
Output Capacitance	C_{oss}			115		
Reverse Transfer Capacitance	C_{rss}			33		
Turn-On Time	$t_{d(on)}$	$V_{DD}=10V, R_L=2.8\Omega$ $I_D=3.6A, V_{GEN}=4.5V$ $R_G=1\Omega$		8	15	ns
	t_r			8	15	
Turn-Off Time	$t_{d(off)}$			25	40	
	t_f			8	15	

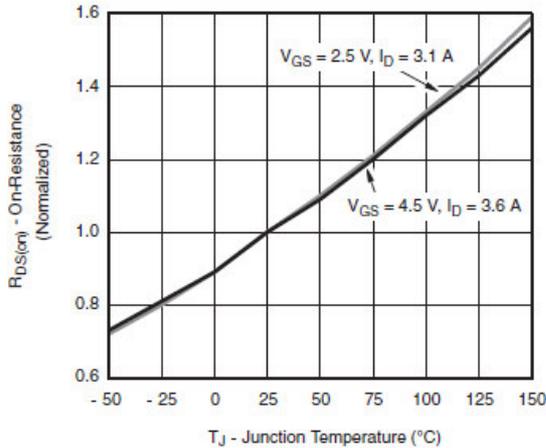


Typical Characteristics

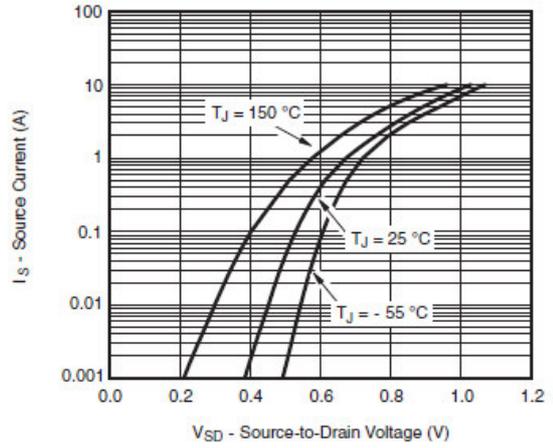




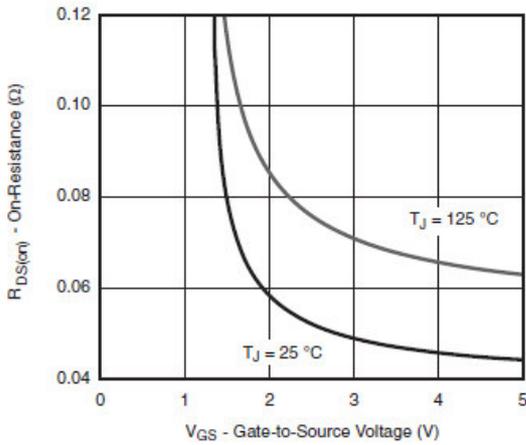
Typical Characteristics



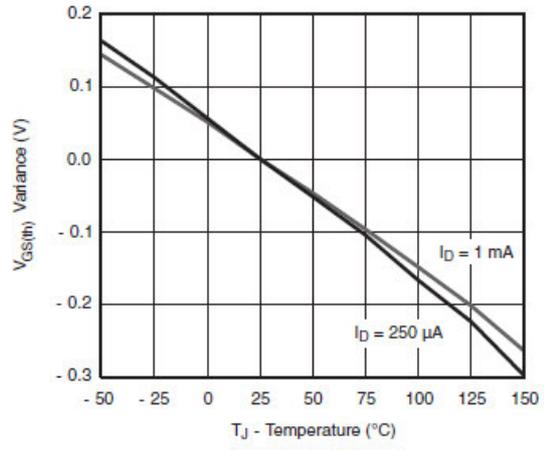
On-Resistance vs. Junction Temperature



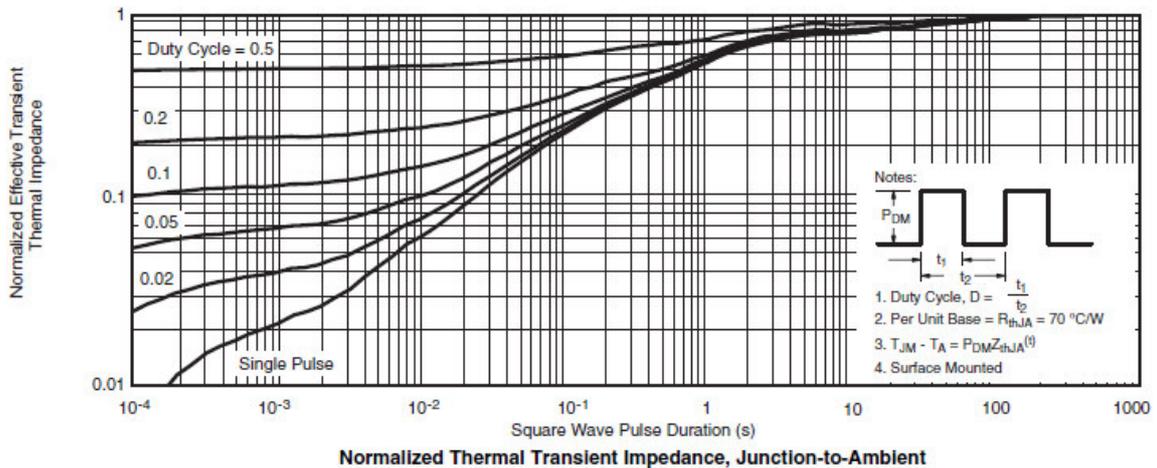
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

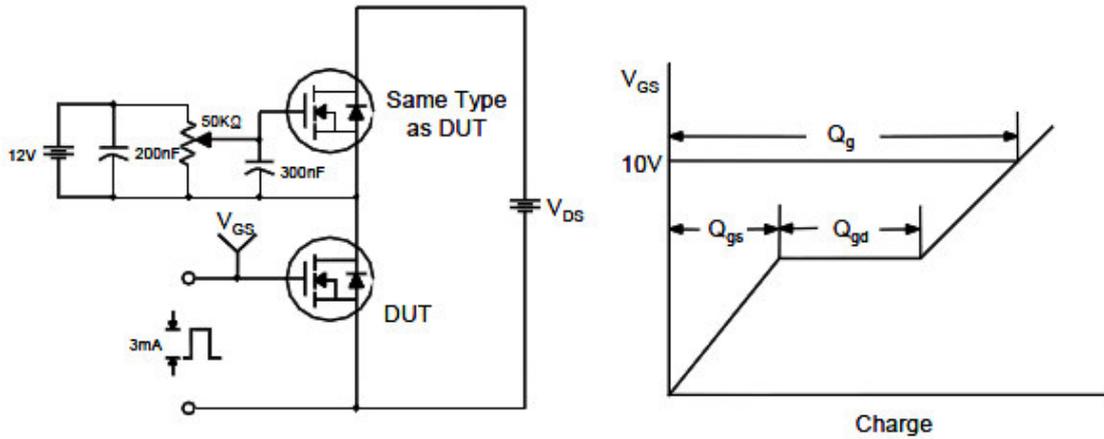


Normalized Thermal Transient Impedance, Junction-to-Ambient

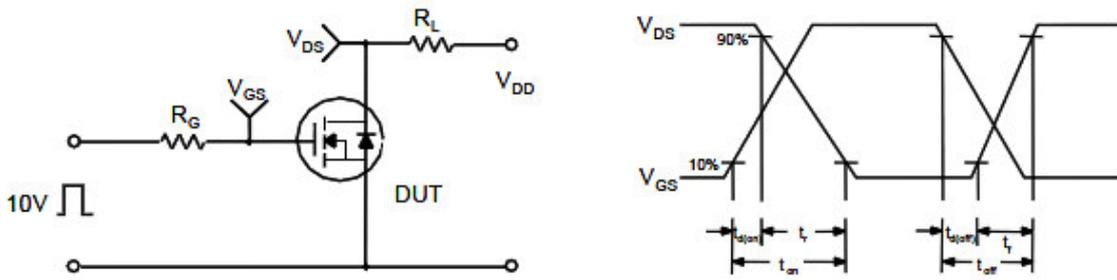


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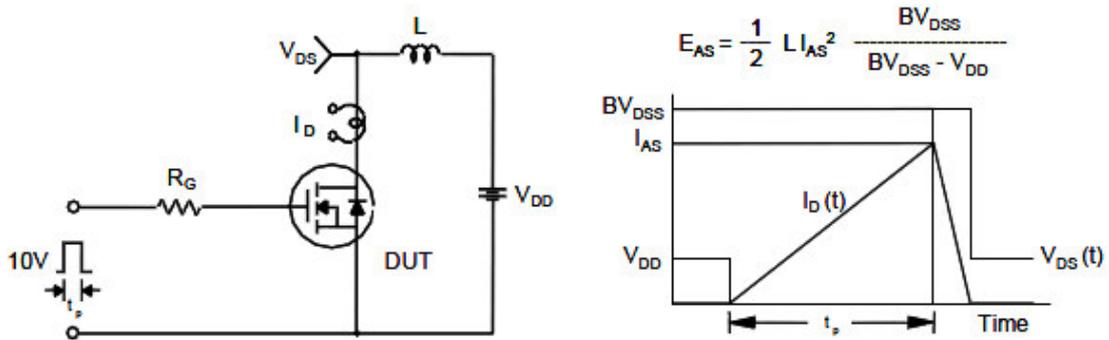
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

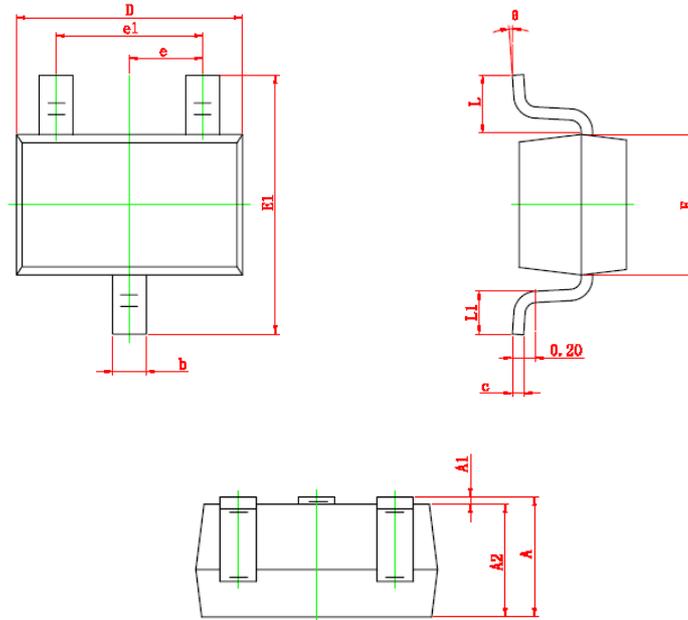


Unclamped Inductive Switching Test Circuit & Waveforms





Package Information (SOT-323)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

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